



- 1. A composition comprising:
- (a) from about 15%/ to about 50%, by weight of the total composition, of a silicone polymer;
- (b) from about 5% to about 30% by weight of the total composition of a reinforcing filler;
- (c) from about 20% to about 70% by weight of the total composition of an anti-tracking agent and a flame retardant;
- (d) from about 0.01% to about 1% by weight of the total composition of a coupling agent;
- (e) from about 0.1% to about 5% by weight of the total composition of a curing agent;
- (f) up to about 20% by weight of the total composition of an extending filler; and
- (g) from about 0.1% to about 5% by weight of the total composition of at least one processing fluid.
 - 2. A composition of claim 1 wherein:
- (a) the silicone polymer comprises from about 25% to about 40%;
 - (b) the reinforcing filler comprises from about 8% to about 20%;
- and (c) the anti-tracking and the flame retardant comprises from about 25% to about 60%.

3. A composition of claim 2 wherein the silicone polymer is represented by recurring units of Formula I

$$R^{3}-O\begin{bmatrix}R^{1}\\ |\\ |\\ |\\ |\\ |\\ |\\ |\\ |\\ |$$

$$R^{1}$$

$$Si-O-R^{3}$$

$$R^{2}$$

$$R^{2}$$

Formula I

wherein:

 R^1 independently at each occurrence represents C_{1-4} alkyl, or

C₂₋₄ alkylene;

R² independently at each occurrence represents C₁₋₄ alkyl,

C₁-C₄ haloalkyl, or C₂₋₄ alkylene;

R³ independently/at each occurrence represents H, C_{1-10} alkyl,

 C_{2-4} alkylene, C_{4-6} cycloalkyl, C_1 -C4 haloalkyl, OH; and

n represents an integer from 1,000 to 20,000

4. A composition of claim 3 wherein

 R^{1} independently at each occurrence represents, CH_{3} or

15 CH=CH₂;

 R^2 independently at each occurrence represents CH_3 , $CH_2CH_2CF_3$, or $CH=CH_2$;

R³ at each occurrence represents CH₃, CH=CH₂, OH, or CH₂CH₂CF₃; and

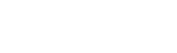
n represents an integer from about 4,000 to about 10,000.

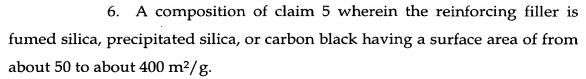
5. A composition of claim 3 wherein the vinyl content of the silicone polymer ranges from about 0.05% to about 0.5 % by weight of the silicone polymer.

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7. A composition of claim 5 wherein the coupling agent is vinyltriethoxysilane (VTES), or vinyltrimethoxysilane, methacrylpropyltrimethoxy silane.

8. A composition of claim 5 wherein the curing agent is a peroxide based curing agent.

9. A composition of claim 8 wherein the curing agent is a diacylperoxide, ketone peroxide, and dialkyl peroxide.

10. A composition of claim 5 wherein the extending filler is ground quartz, calcium carbonate, magnesium silicate, or magnesium aluminum silicate.

M. A process of claim 5 wherein the processing fluid is a methyl or hydroxy terminated polydimethyl siloxane.

- 12. A composition of claim 5 further comprising a mold release agent, a coloring agent, or a heat resistive agent.
- 13. A composition of claim 12 wherein the mold release agent is a silicone fluid, magnesium, aluminum, or cerium stearate.
- 14. A composition of claim 13 wherein the heat resistive agent is a cerium octoate, cerium hydroxide, magnesium oxide, cerium oxide, or magnesium hydroxide.
 - 15. A composition of claim 1 wherein upon heat curing the composition, the heat cured composition comprises a high voltage insulating composition.
 - 16. A process for making a high voltage insulating composition, the process comprising heat curing the composition of claim 1.

